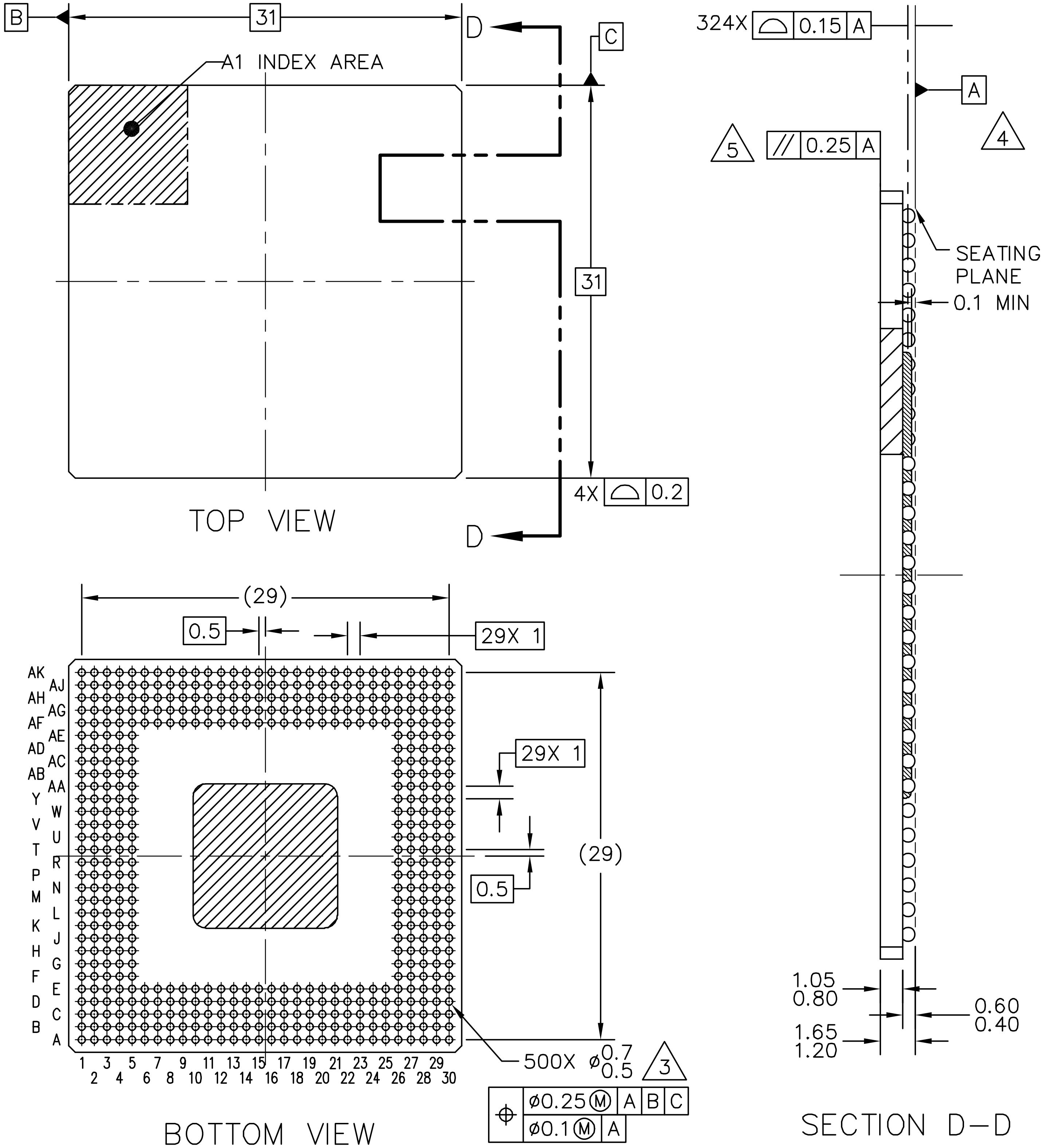

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TITLE: 500 I/O TAPE BGA, 31 X 31 PKG, 1 MM PITCH	DOCUMENT NO: 98ARS10509D	REV: A
	CASE NUMBER: 1475–01	18 AUG 2005
	STANDARD: JEDEC MO–192, VARIATION AAN–1	

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M−1994.

△3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

△4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

△5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

MECHANICAL OUTLINE

PRINT VERSION NOT TO SCALE

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